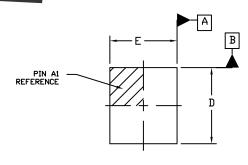


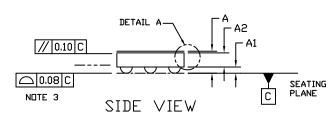
WLCSP6 1.11x0.98x0.35

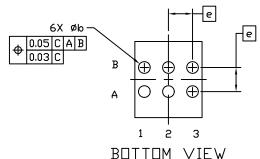
CASE 567ZZ **ISSUE O**

DATE 09 NOV 2021



TOP VIEW





GENERIC MARKING DIAGRAM*



XXXX = Specific Device Code = Assembly Location

= Year ww = Work Week

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "■", may or may not be present. Some products may

NOTES:

NOTE 6

АЗ

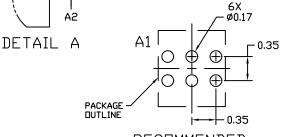
A2

BACKSIDE

COATING

- 1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
- CONTROLLING DIMENSION: MILLIMETERS
- COPLANARITY APPLIES TO THE SPHERICAL CROWNS OF THE SOLDER BALLS.
- 4. DATUM C, THE SEATING PLANE, IS DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.
- 5. DIMENSION & IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER PARALLEL TO DATUM C.
- BACKSIDE COATING IS OPTIONAL.

	MILLIMETERS		
DIM	MIN.	MAX.	
Α	-	0.35	
A1	0.080	0.100	
A2	0.205 REF		
A3	0.025 REF		
b	0.15	0.19	
D	1.091	1.121	
Ε	0.961	0.991	
e	0.35 BSC		



RECOMMENDED MOUNTING FOOTPRINT

DESCRIPTION:	WLCSP6 1.11x0.98x0.35		PAGE 1 OF 1
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